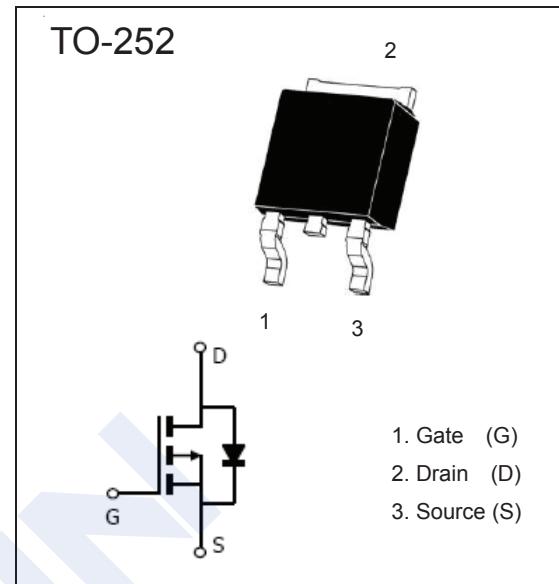


P-Channel MOSFET

2KJ6056

■ Features

- Advanced Process Technology
- Surface Mount
- 175°C Operating Temperature
- Fast Switching
- P-Channel
- Fully Avalanche Rated

■ Absolute Maximum Ratings ($T_J = 25^\circ\text{C}$ Unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-150	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current ($T_c = 25^\circ\text{C}$)	I_D	-21	A
($T_c = 100^\circ\text{C}$)		-14.9	
Pulsed Drain Current *1	I_{DM}	-84	
Single pulse avalanche energy *2	E_{AS}	310	mJ
Power Dissipation	P_D	110	W
Thermal Resistance, Junction- to-Ambient *3	$R_{\theta JA}$	50	°C/W
Thermal Resistance, Junction- to-Case	$R_{\theta JC}$	1.4	
Junction Temperature	T_J	175	°C
Junction Storage Temperature Range	T_{stg}	-55 to 175	

Notes:

*1.limited by maximum junction temperature.

*2. EAS condition: starting $T_J = 25^\circ\text{C}$, $L = 14\text{mH}$, $R_G = 25\Omega$, $I_{AS} = -6.6\text{A}$.

*3. Surface Mounted on FR4 Board, $t \leq 10$ sec.

2KJ6056

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	V(BR)DSS	VGS = 0V, ID = -250 μ A	-150			V
Breakdown Voltage Temp. Coefficient	△V(BR)DSS/△TJ	ID = -1mA, Reference to 25°C		-0.02		V/°C
Static Drain-to-Source On-Resistance	RDS(on)	VGS = -10V, ID = -6.6A*1		95		mΩ
		VGS = -10V, ID = -6.6A, TJ = 150°C*1		225		
Gate Threshold Voltage	VGS(th)	VDS = VGS, ID = -250 μ A	-0.7		-2.0	V
Forward Transconductance	gfs	VDS = -50V, ID = -6.6A*1	3.6			S
Drain-to-Source Leakage Current	IDSS	VDS = -120V, VGS = 0V		-1		μ A
		VDS = -120V, VGS = 0V, TJ = 150°C		-250		
Gate-to-Source Forward Leakage	IGSS	VGS = 20V		100		nA
Gate-to-Source Reverse Leakage		VGS = -20V		-100		
Total Gate Charge	Qg	ID = -6.6A		66		nC
Gate-to-Source Charge	Qgs	VDS = -120V		8.1		
Gate-to-Drain ("Miller") Charge	Qgd	VGS = -10V,*1		35		
Turn-On Delay Time	t _{d(on)}	VDD = -75V ID = -6.6A RG = 6.8 Ω RD = 12 Ω*1		14		ns
Rise Time	t _r			36		
Turn-Off Delay Time	t _{d(off)}			53		
Fall Time	t _f			37		
Internal Drain Inductance	L _D	Between lead, 6mm (0.25in.) from package and center of die contact		4.5		nH
Internal Source Inductance	L _S			7.5		nH
Input Capacitance	C _{iss}	VGS = 0V VDS = -25V f = 1.0MHz		860		pF
Output Capacitance	C _{oss}			220		
Reverse Transfer Capacitance	C _{rss}			130		
Continuous Source Current (Body Diode)	I _s	MOSFET symbol showing the integral reverse p-n junction diode.			-21	A
Pulsed Source Current (Body Diode)*2	I _{SM}				-44	
Diode Forward Voltage	V _{SD}	T _J = 25°C, I _s = -6.6A, V _{GS} = 0V*1			-1.6	V
Reverse Recovery Time	t _{rr}	T _J = 25°C, I _F = -6.6A di/dt = 100A/ μ s*1		160	560	ns
Reverse RecoveryCharge	Q _{rr}			1.2	1.7	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _s +L _D)				

*1 Pulse width ≤ 300 μ s; duty cycle ≤ 2%.

*2 Repetitive rating; pulse width limited by max. junction temperature.

■ Marking

Marking	J6056 K***
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2KJ6056

■ Typical Electrical and Thermal Characteristics

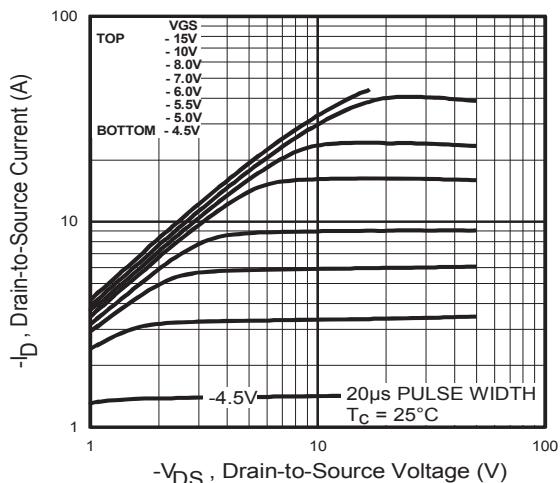


Fig. 1 Typical Output Characteristics

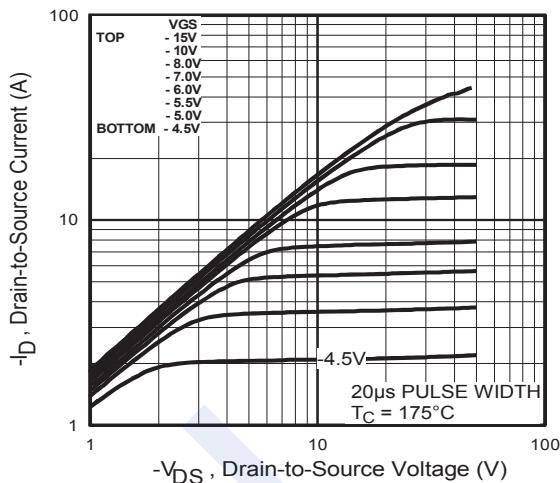


Fig. 2 Typical Output Characteristics

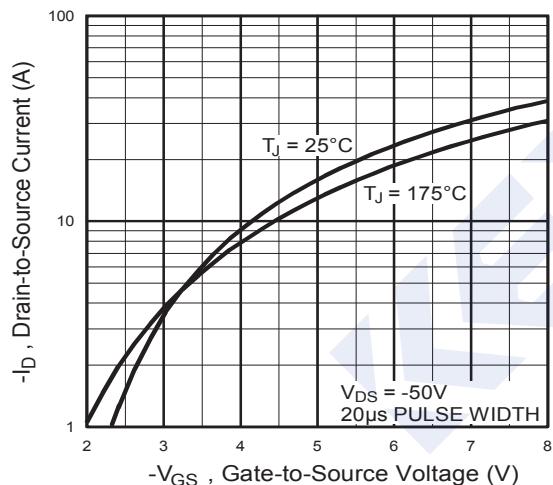


Fig. 3 Typical Transfer Characteristics

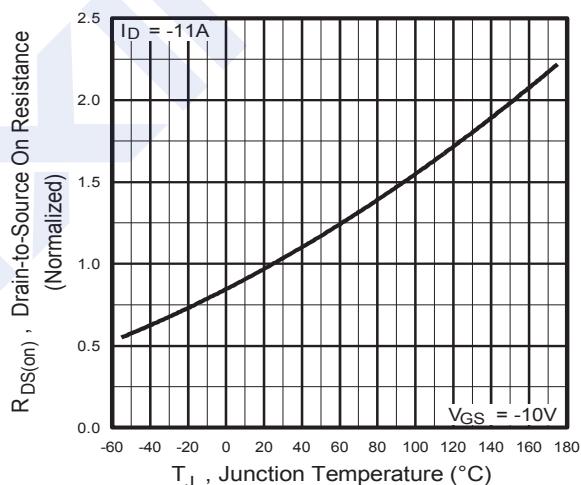


Fig. 4 Normalized On-Resistance vs. Temperature

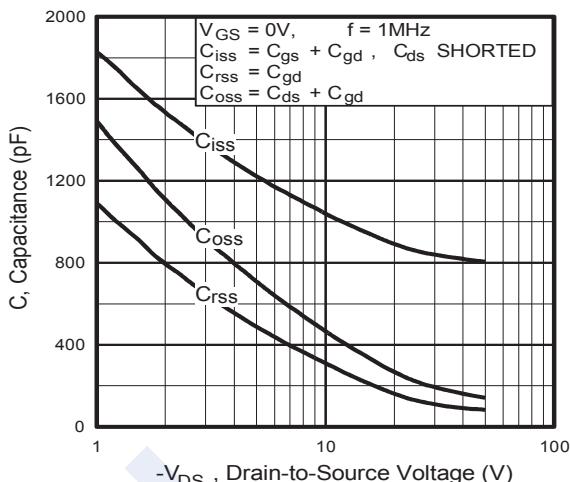


Fig. 5. Typical Capacitance vs. Drain-to-Source Voltage

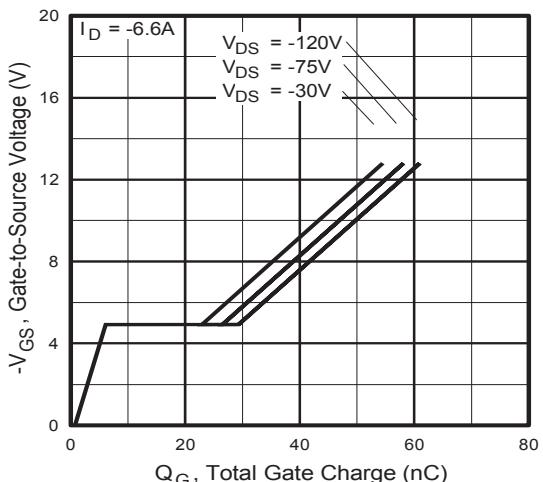


Fig. 6. Typical Gate Charge vs. Gate-to-Source Voltage

2KJ6056

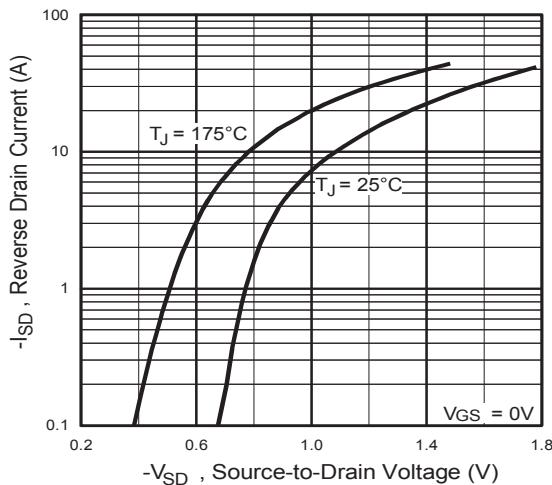


Fig. 7 Typical Source-to-Drain Diode Forward Voltage

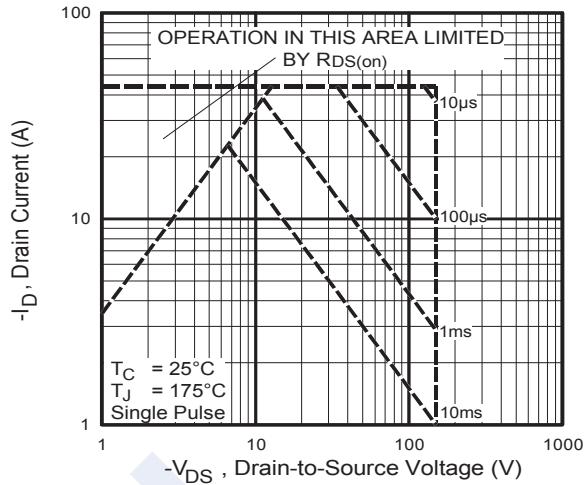


Fig. 8. Maximum Safe Operating Area

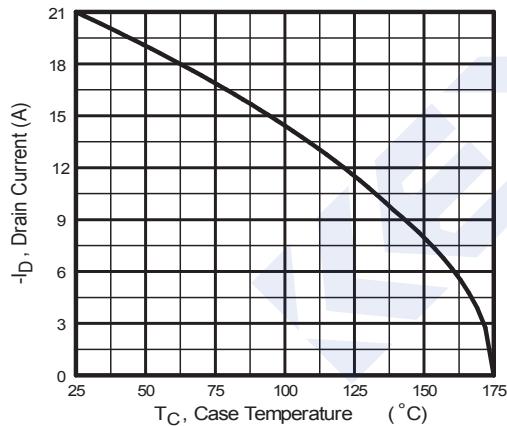


Fig. 9. Maximum Drain Current vs. Case Temperature

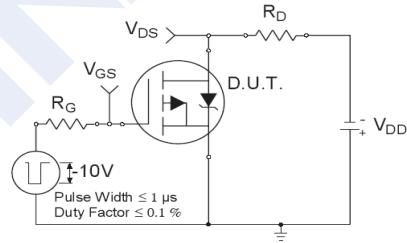


Fig 10a. Switching Time Test Circuit

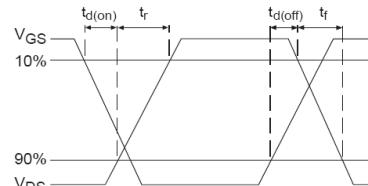


Fig 10b. Switching Time Waveforms

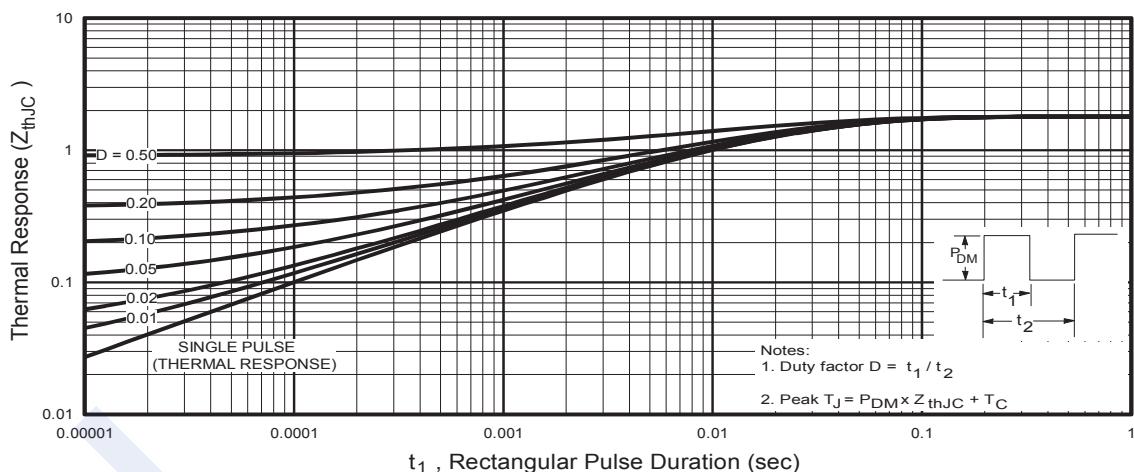
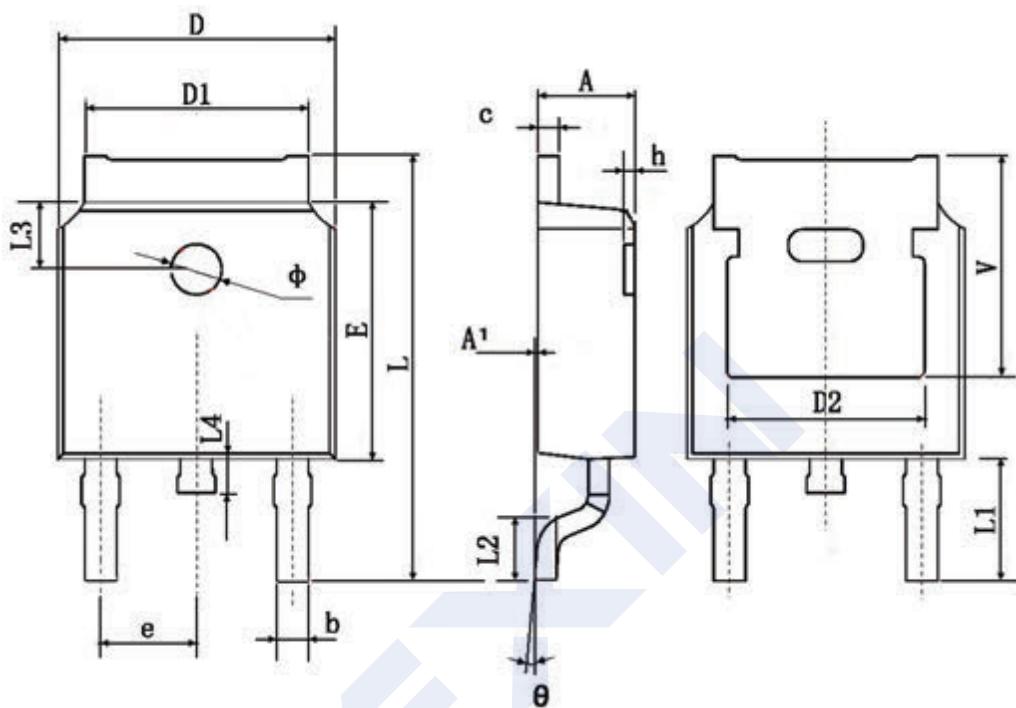


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

2KJ6056

■ Package Dimension

TO-252



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	